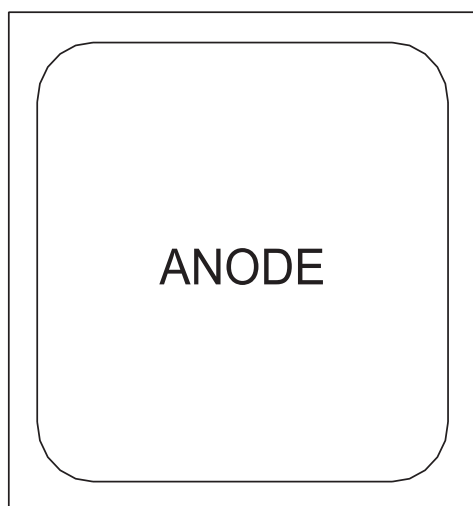


**PROCESS DETAILS**

|                        |                       |
|------------------------|-----------------------|
| Process                | GLASS PASSIVATED MESA |
| Die Size               | 98 x 98 MILS          |
| Die Thickness          | 10.4 MILS             |
| Anode Bonding Pad Area | 82.5 x 82.5 MILS      |
| Top Side Metalization  | Au - 5,000Å           |
| Back Side Metalization | Au - 2,000Å           |

**GEOMETRY**



BACKSIDE CATHODE

R0

**GROSS DIE PER 4 INCH WAFER**

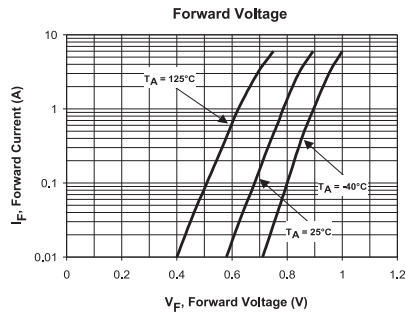
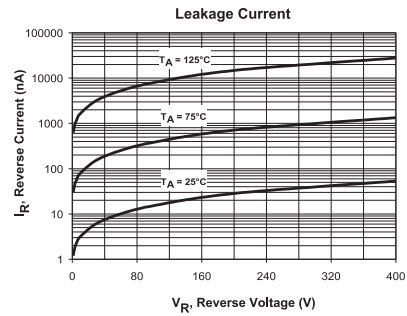
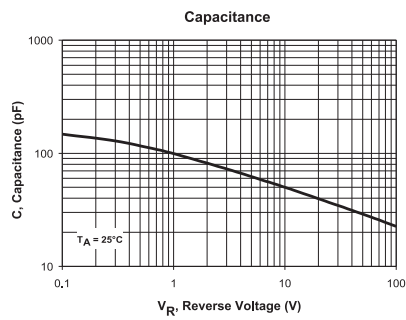
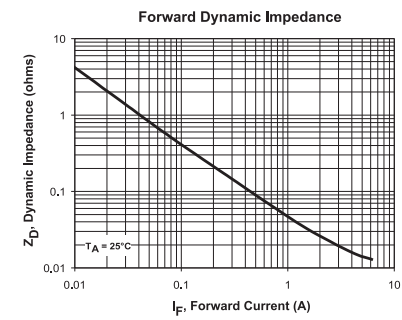
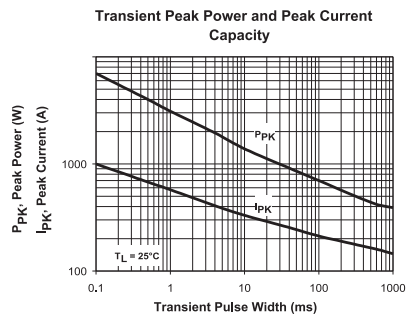
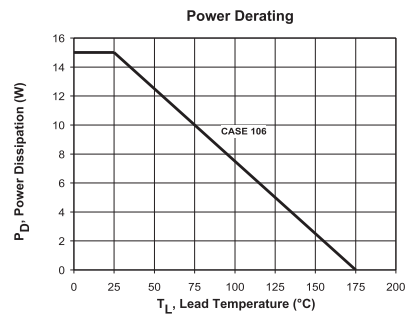
1,170

**PRINCIPAL DEVICE TYPES**

CR6A2GPP Series

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